SUSS MICROTEC INVESTOR PRESENTATION

April 2016

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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SUSS MICROTEC AT A GLANCE

- **Global leader in manufacturing equipment for semiconductor devices**
- **SUSS’ Equipment creates micro structures that connect micro electronic devices**
- **Focus on growth segments: advanced packaging, MEMS, and 2.5D / 3D Integration**
- **Attractive end markets: smartphones, tablets, automotive, LED, sensors, IoT, …**

- **Sales FY 2015: €148.5 million**
- **EBIT FY 2015: € 5.0 million (EBIT-margin: 3.4%)**
- **Net Cash 2015: € 40.0 million**
- **Market Cap 03/24/2016: € 185 million**

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA
Order Entry 27.6 € million
Sales 28.0 € million
Employees 116

EMEA
Order Entry 48.8 € million
Sales 40.5 € million
Employees 448

ASIA
Order Entry 112.2 € million
Sales 80.0 € million
Employees 134

■ Headquarters
▨ Production
🟦 Sales

🟦 ▨ Corona, US

■ ▨ Garching, DE
▨ Sternenfels, DE
▨ Hauterive, CH
🟦 Lyon, FR
🟦 Market Rasen, UK

🟦 Singapore, SG

🟦 Yokohama, JP
🟦 Hwaseong City, KR
🟦 Shanghai, CN
🟦 HsinChu, TW

*Figures refer to the fiscal year 2015

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SUSS MICROTEC IN THE VALUE CHAIN

SÜSS MicroTec

- **Semiconductor Manufacturing Equipment**
- **Micro Structuring**

Research Institutes

Semiconductor Manufacturers

- Semiconductor Devices
- ICs
- Sensors
- Microoptics

Enterprise Products

- Servers
- Interfaces
- Power Distribution
- Cloud Computing

Consumer Products

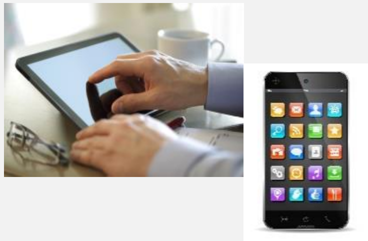
- Smartphones
- Tablets, PCs
- Automotive
- Medical Devices
- Gaming
- Lighting

+ **SUSS MicroTec:**
  - Key player in leading edge semiconductor manufacturing equipment
  - Developer of highly innovative process solutions
+ Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment

MARKET DRIVERS

Connectivity & Data Processing

- Connection through apps, social media, data streaming
- Connectivity of devices, Internet of Things (IoT)
- Permanent internet connectivity provided by smartphones and tablet PCs at affordable cost
- Industry 4.0 connectivity of manufacturing units



Mobility & Automotive

- Autonomous, electric and plug in hybrid cars, E-Bikes, trains drive the need for power devices and high performance ICs at the same time
- Growing electronic content and sensors (MEMS) for autonomous cars

Energy Efficiency

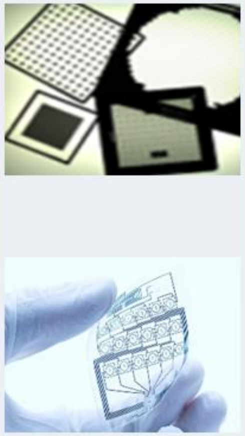
- Environmental awareness and rising energy costs drive the demand for energy efficient devices
- Energy efficiency in industrial production
- Smart energy management in household applications
- Green energy management systems

KEY MARKETS - OVERVIEW

Semiconductors

Front End Lithography

- Photomask Cleaning

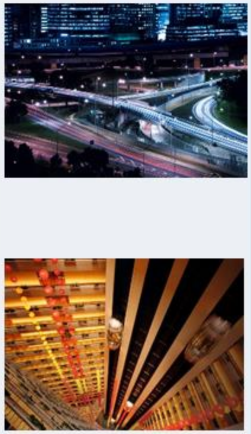


Advanced Packaging

- Micro-Bumping
- Fan-Out WLP
- Cu Pillar

Chipset Integration

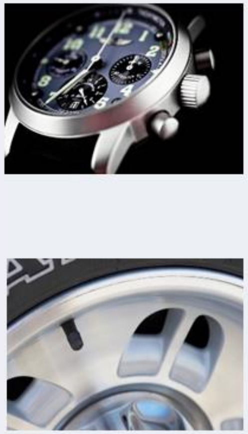
- 3D (TSV) Stacking
- 2.5D Integration



Sensors

MEMS

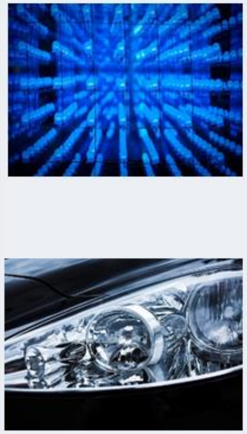
- Internet of Things
- Automotive
- Mobile Devices
- Industry 4.0
- Biomedical



Lighting

LED

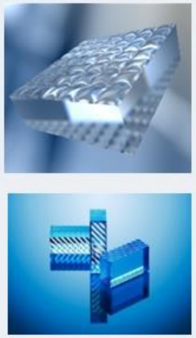
- General Lighting
- HB and UHB



Micro Optics

Advanced Optics

- Wafer Level Optics
- Fiber Optics
- Laser and Lithography Beam Shaping Optics



Micro Optical Components

Micro lens arrays
Diffractive optical elements

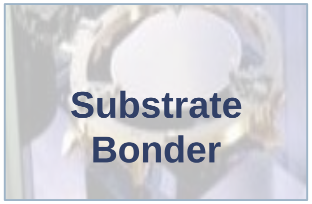
SEGMENTS AND MARKETS

Frontend

Mid- and Backend

Photomask Equipment

Lithography



Substrate Bonder

Photomask Cleaning Equipment	Laser Processing Equipment	Exposure Systems	Coaters and Developers	Wafer Bonding Equipment

Photomask Business

Advanced packaging (WLP, FOWLP, Copper Pillar…)

2.5D and 3D integration

MEMS

LED

Adjacent Markets

Micro Optics

SEGMENTS AND PRODUCTS

Frontend

Mid- and Backend

Photomask Equipment

Photomask Cleaning Equipment

MaskTrack*Pro*

Lithography

Laser Processing Equipment

ELP300

Exposure Systems

Mask Aligner
MA200/300 Gen2

Projection Scanner
DSC300 Gen2

Coaters and Developers

ACS300 Gen2

Substrate Bonder

Wafer Bonding Equipment

XBC300 Gen2

XB8

SEGMENTS AND FINANCIALS

Divisions


Photomask Equipment


Lithography


Substrate Bonder

Photomask Cleaning Equipment

Laser Processing Equipment

Exposure Systems

Coaters and Developers

Wafer Bonding Equipment

Order Entry: 21.5 € million
Sales: 23.5 € million
EBIT margin: 9.9%

Order Entry: 149.6 € million
Sales: 106.3 € million
EBIT margin: 9.1%

Order Entry: 10.5 € million
Sales: 11.4 € million
EBIT margin: -34.7%

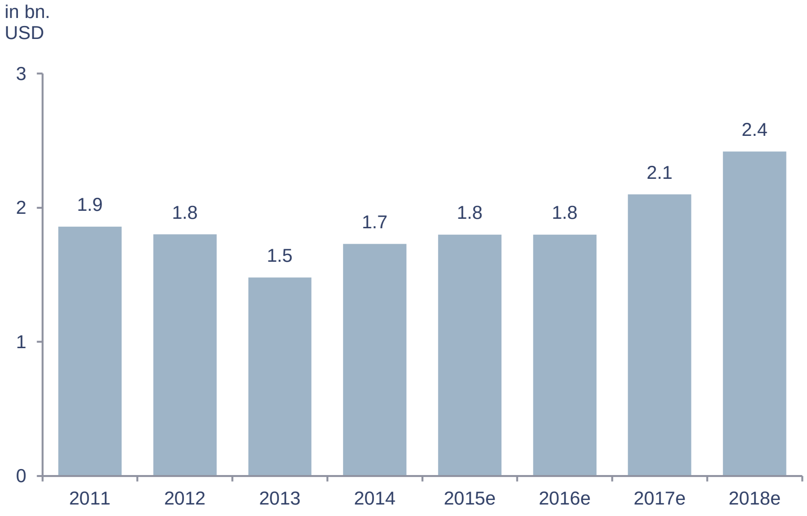
SUSS MicroTec Group FY 2015

Order Entry: 188.6 € million
Sales: 148.5 € million

EBIT: 5.0 € million
EBIT margin: 3.4%

KEY MARKETS – ADVANCED PACKAGING

Wafer-level packaging (WLP) and assembly equipment



Source: Gartner, January 2016

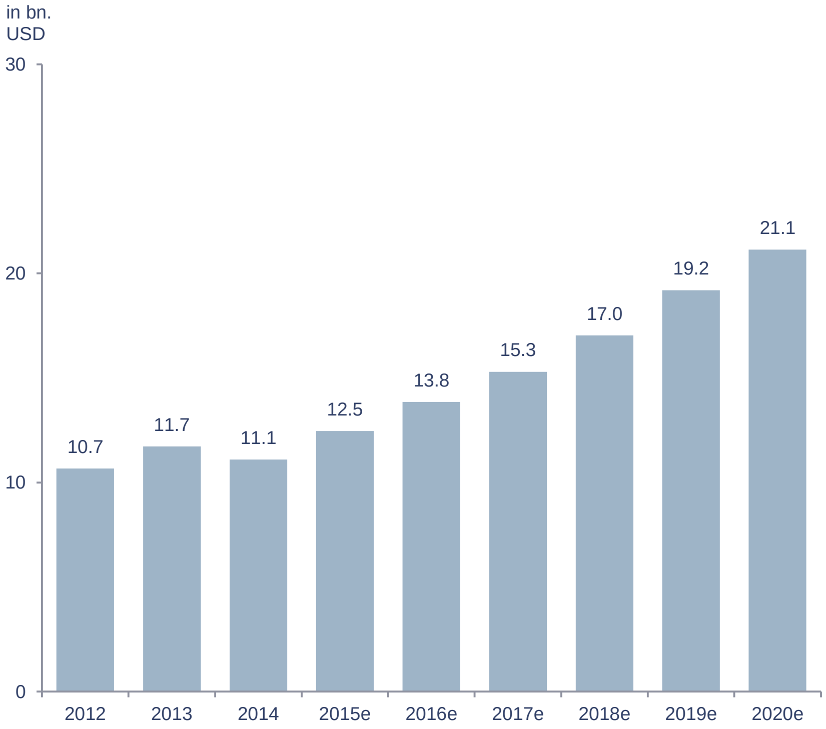
+ **Attractive growth opportunities within wafer-level packaging:**
  - **Fan-out WLP**
  - **Copper pillar**
  - **Bumping**

+ **Grow market share for core products in advanced packaging: coater/developer, mask aligner**

+ **Achieve traction for new advanced lithography products from SUSS MicroTec Photonic Systems:**
  - Further HVM orders for scanner products
  - Qualification of laser products at key customers

KEY MARKETS – MEMS

MEMS market



Source: Yole, May 2015

- **Internet of Things (IoT)**
- **Smartphones and tablets**
- **Automotive applications**
- **Health/biomedical applications**
- **Grow market share for core products for MEMS: coater/developer, mask aligner, substrate bonder**
- **Market re-entry permanent bonder with new differentiated product**

IC SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

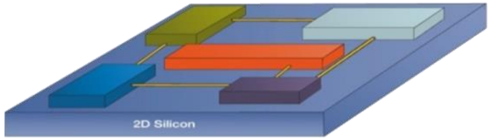
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple patterning drive further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

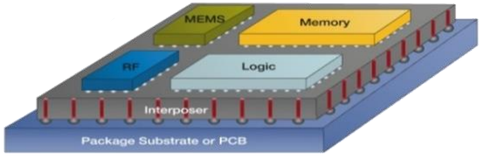
2.5D Packaging

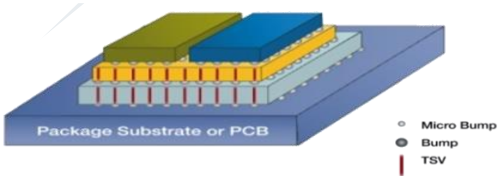
- Combining of several devices on an interposer addresses the limitations of traditional shrinking while enhancing performance
- Increased packaging density
- Reduced footprint
- Packaging becomes enabler and addresses performance slow down of Moore‘s Law

3D Integration (TSV)

- Stacking of several devices horizontally enables high performance at a low footprint
- TSV and bonded thin Si technology becomes key enabler for scaling
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption







SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 2.5D / 3D integration ("*More than Moore*")

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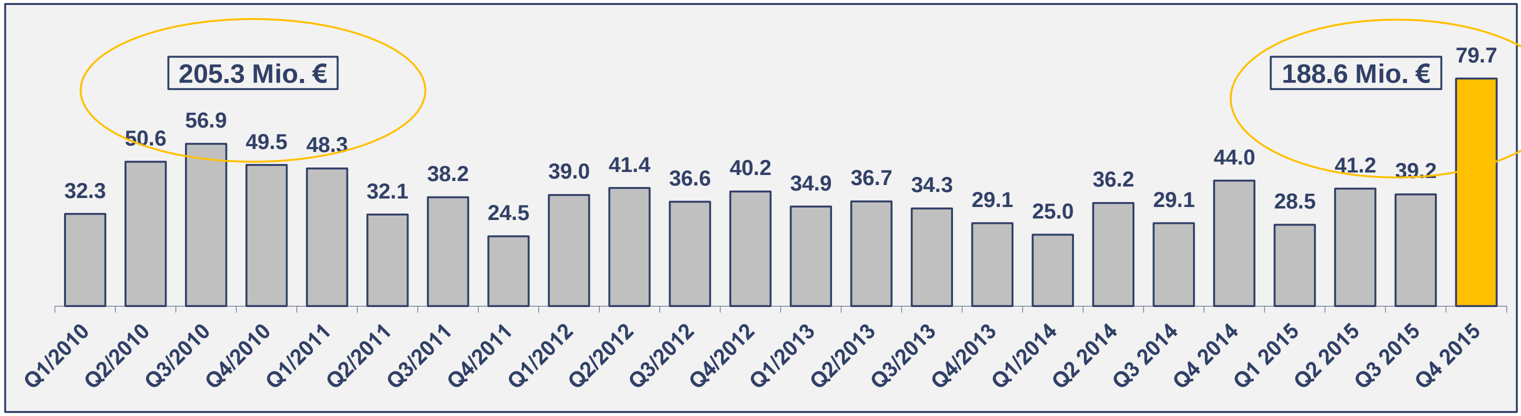
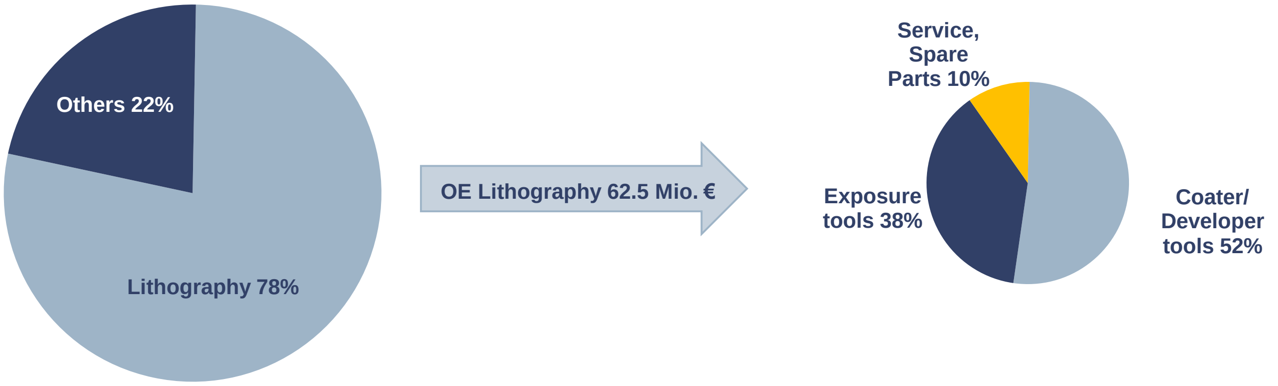
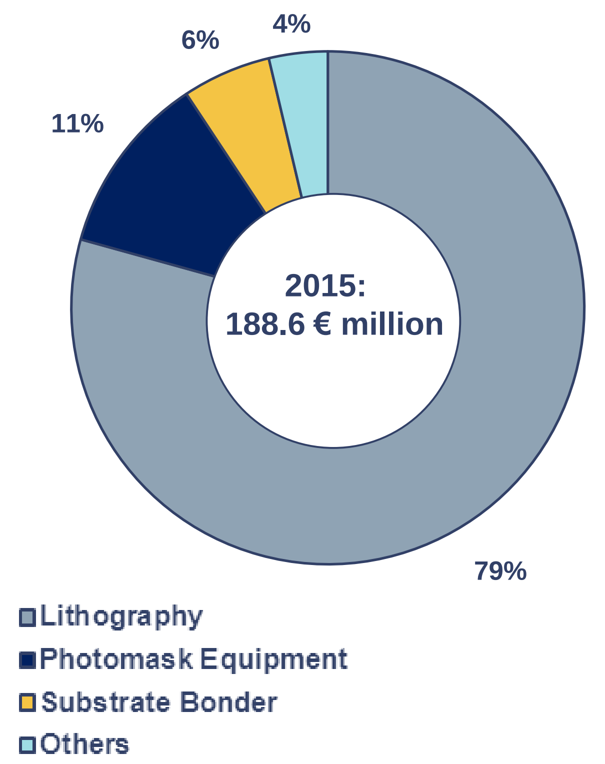
ORDER ENTRY Q4 2015 AT RECORD LEVEL



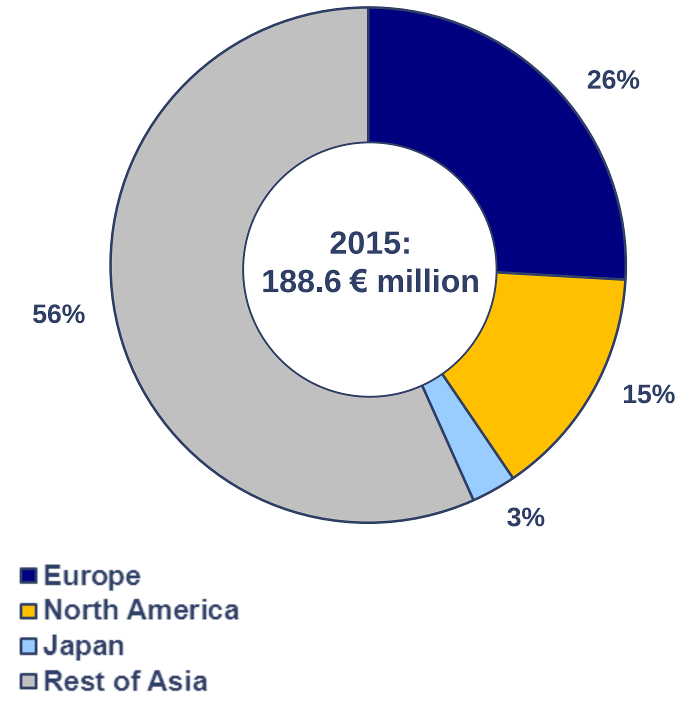


ORDER ENTRY AND SALES BY SEGMENT AND REGION 2015

Order Entry by Segment

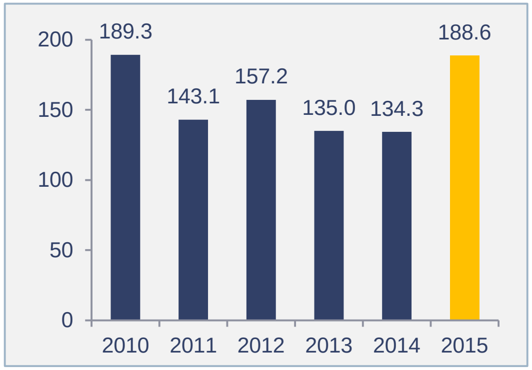


Order Entry by Region

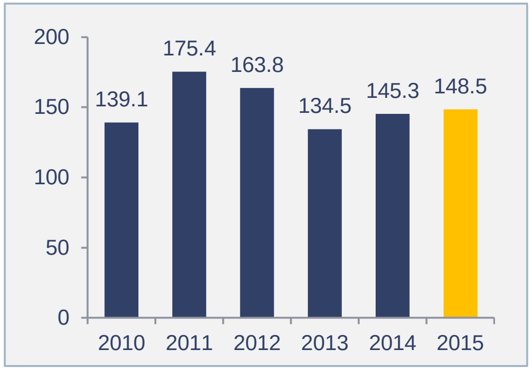


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

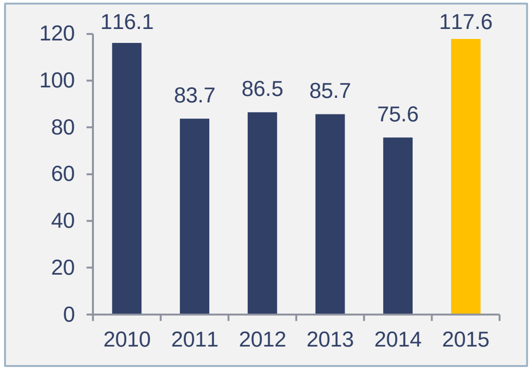
Order Entry in € million



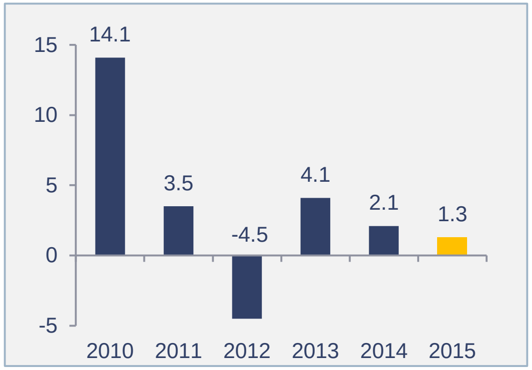
Sales in € million



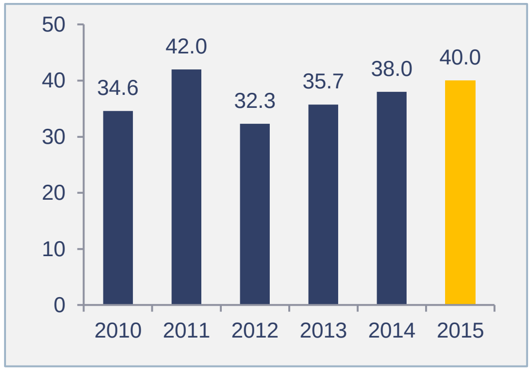
Order Backlog in € million



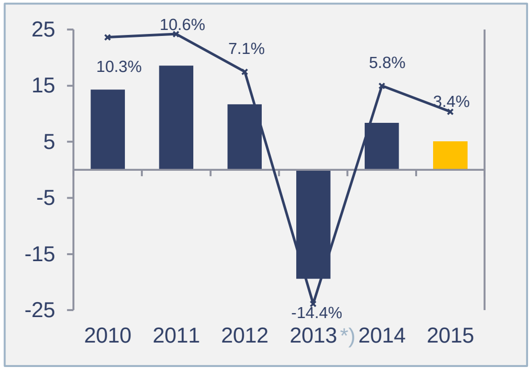
Free Cash Flow in € million



Net Cash in € million



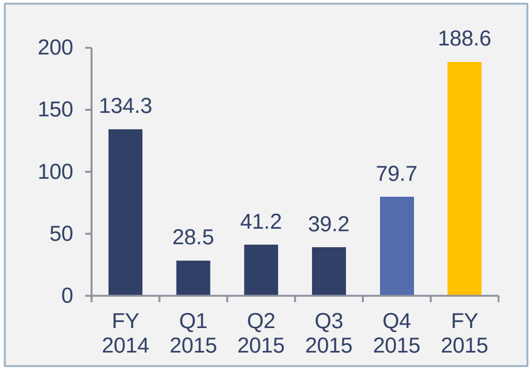
EBIT in € million



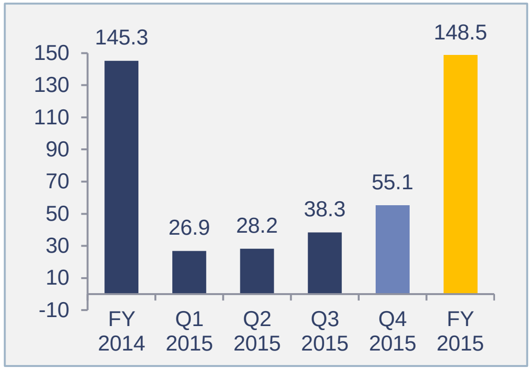
* Including a -13.2 € milion one-off effect from restructuring of the product line permanant bonding (-0,69 € per share)

2015 - P&L KEY FIGURES BY QUARTER

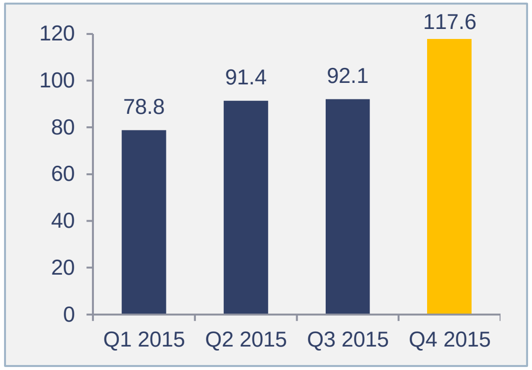
Order Entry in € million



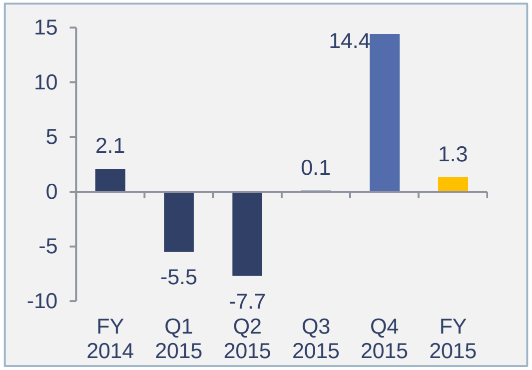
Sales in € million



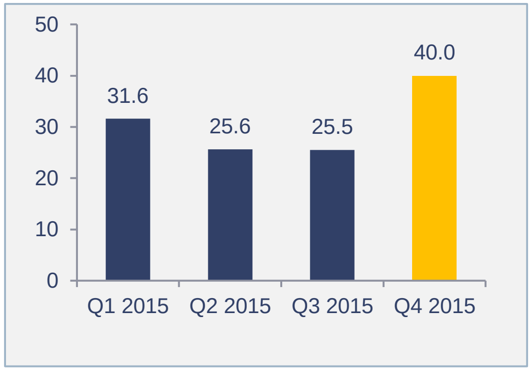
Order Backlog in € million



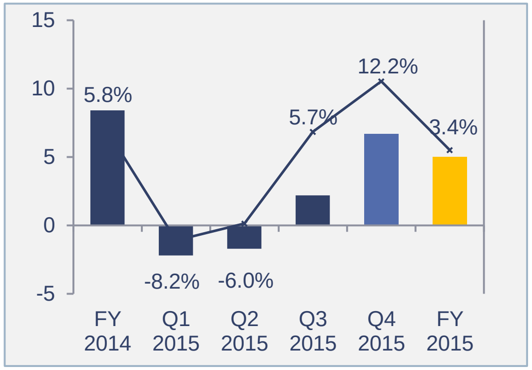
Free Cash Flow in € million



Net Cash in € million



EBIT in € million



KEY FINANCIALS

in € million	2015	2014	in %
Order Intake	**188.6**	**134.3**	**+40.4%**
Order Backlog 12/31	**117.6**	**75.6**	**+55.6%**
Revenue	**148.5**	**145.3**	**+2.2%**
EBIT	**5.0**	**8.4**	**-40.5%**
EBIT in % of Sales	*3.4%*	*5.8%*	*-2.4%pt.*
Earnings after tax	**0.2**	**4.6**	**-95.7%**
EPS in €	**0.01**	**0.24**	**-95.8%**
Net Cash*	**40.0**	**38.0**	**+5.3%**
Free Cash Flow**	**1.3**	**2.1**	**-38.1%**
Employees 12/31	**698**	**659**	**+5.9%**

* before consideration of purchased / sold interest-bearing securities

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ROADMAP TARGETS

Short-term

- Grow market share for core products in all market segments
- Traction for new advanced lithography products from SUSS MicroTec Photonic Systems
- Stabilize Company at positive EBIT and cash generation, continue revenue growth:
  - Gross margin 30-35%

Mid-term

- Focused product portfolio
- Positive EBIT from Bonder Division and Photonic Systems
- Successful new adjacent market entries (leverage existing technologies to grow SAM)
- Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35%
  - EBIT margin >5%

Long-term

- Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35%
  - EBIT margin 10%

OUTLOOK 2016

Market Outlook

- Market environment becomes challenging in 1H 2016 and customers become more cautious with investments
- Outlook of SUSS MicroTec and our peer group is cautiously optimistic for H2 2016
- Market analysts expect the semi market to grow by 1 - 2% in 2016
- Market for WLP and assembly equipment expected to be flat
- Market forecasts show a return to the growth path in WLP and assembly with double digit yoy growth in 2017 and 2018

SUSS MicroTec Outlook

- FY 2016: Sales 170 - 180 € million
  EBIT 9 – 13 € million
- Q1 2016: Order Intake 25 - 35 € million

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INVESTOR RELATIONS INFORMATION

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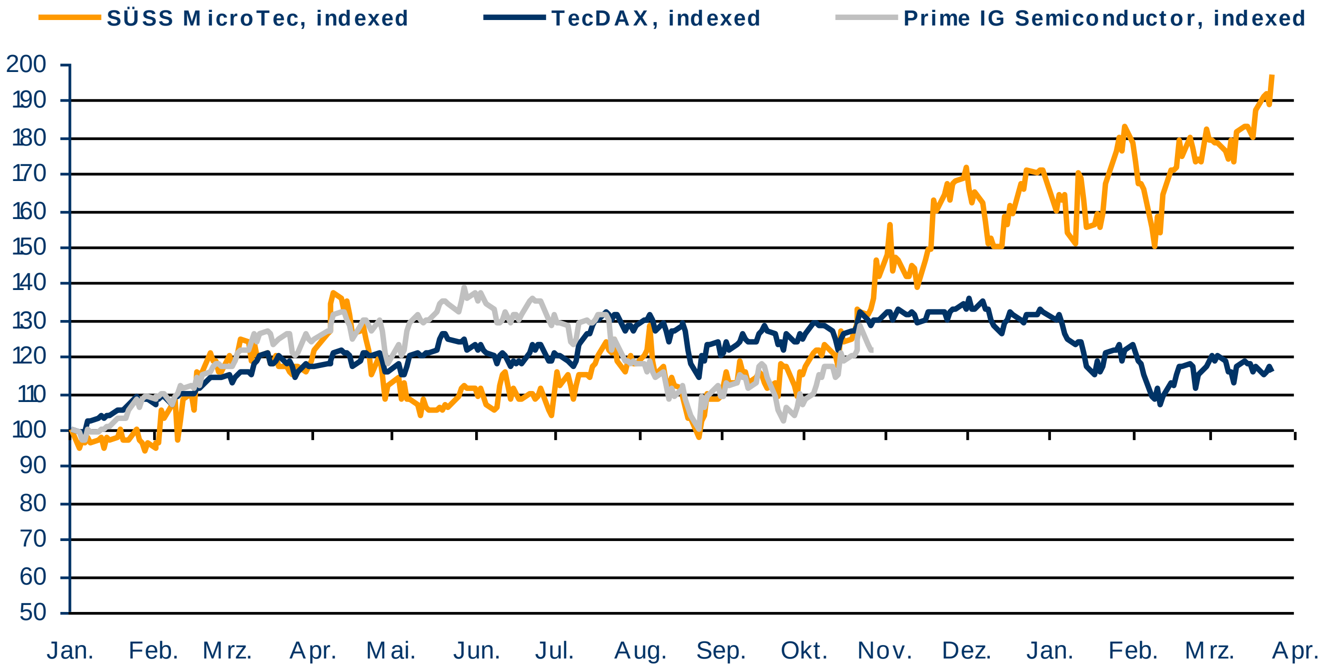
Financial Calendar 2016

KeplerCheuvreux Investment Conference, Frankfurt	20 Jan
Annual Report 2015	30 Mar
Quarterly Report 2016	4 May
Annual General Meeting 2016, Munich	15 Jun
Interim Report 2016	5 Aug
Nine-month Report 2016	9 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2015: 4.88 €)



Major Shareholders:

Henderson	5.1%
Universal	4.9%
Sycomore	3.1%
INKA	3.1%
Dimensional	3.0%
Baillie Gifford	3.0%

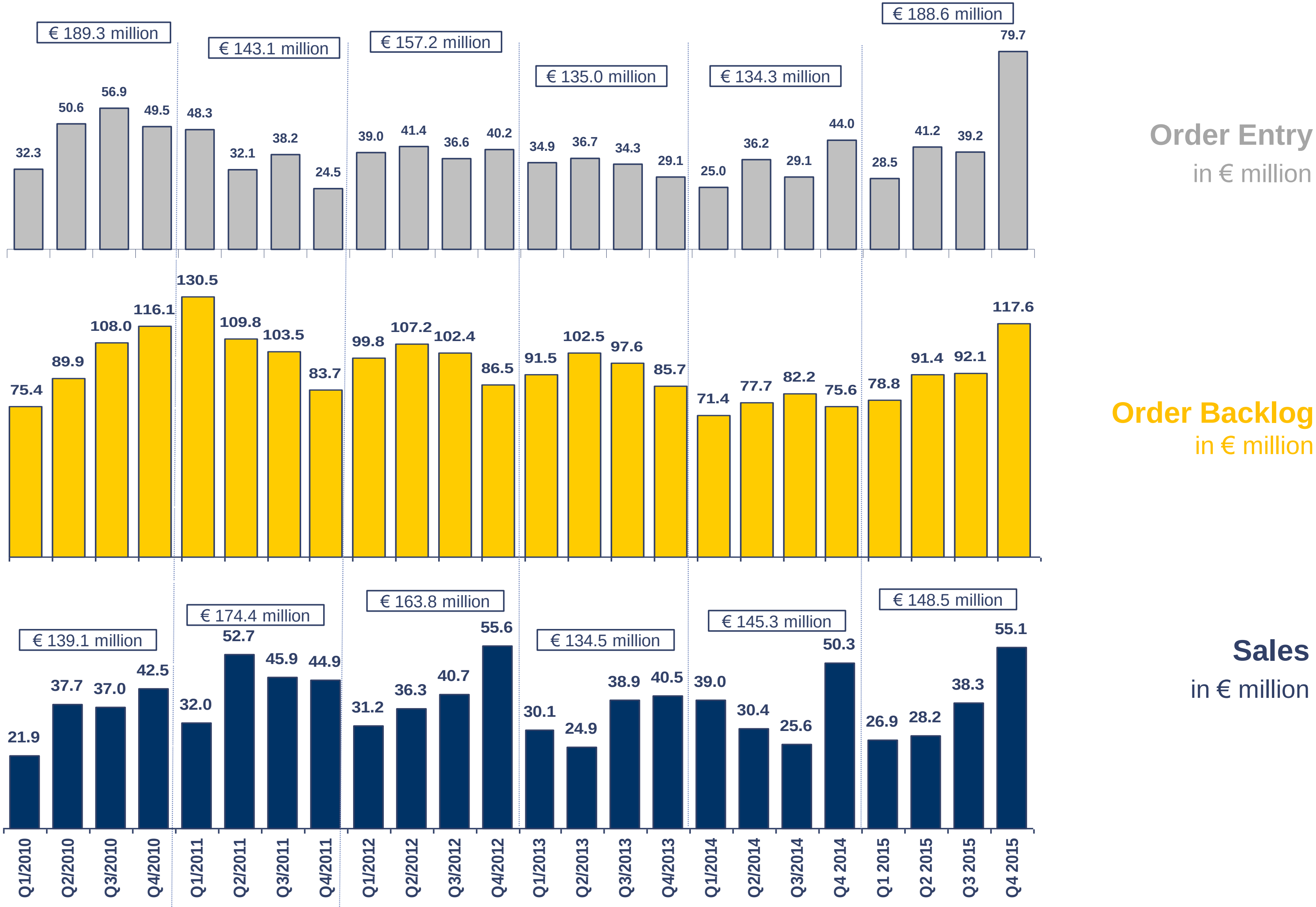
TecDAX re-entry in March 2016

Average daily trading volume January 2015 – March 2016: ~ 165,000

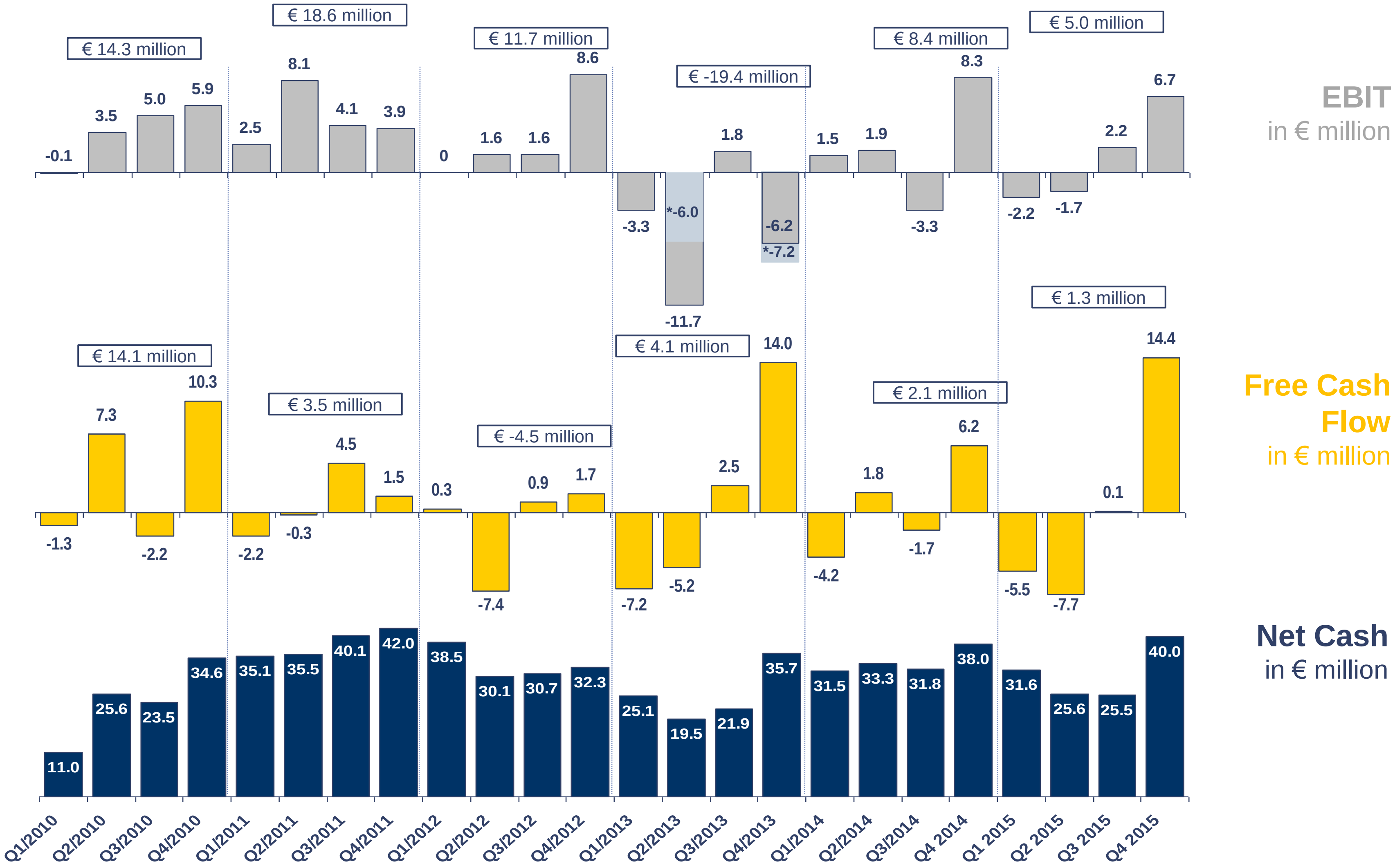
ANALYST ESTIMATES

Date	Institution	Analyst	Recommendation	Target
11.02.2016	Hauck & Aufhäuser	Tim Wunderlich	Buy	12,50 EUR
15.02.2016	Baader Bank AG	Günter Hollfelder	Buy	8,00 EUR
24.03.2016	Warburg Research	Malte Schaumann	Buy	12,00 EUR
24.03.2016	DZ Bank AG	Harald Schnitzer	Hold	7,50 EUR
11.02.2016	Kepler Cheuvreux	Bernd Laux	Hold	8,00 EUR
11.02.2016	Berenberg	Tammy Qiu	Buy	9,00 EUR
12.02.2016	equinet Bank AG	Adrian Pehl	Auccumulate	8,50 EUR
28.01.2016	Bankhaus Lampe	Dr. Karsten Iltgen	Hold	8,00 EUR
08.05.2015	Oddo Seydler	Veysel Taze	Buy	6,00 EUR
13.08.2014	Deutsche Bank	Uwe Schupp	Buy	9,00 EUR

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

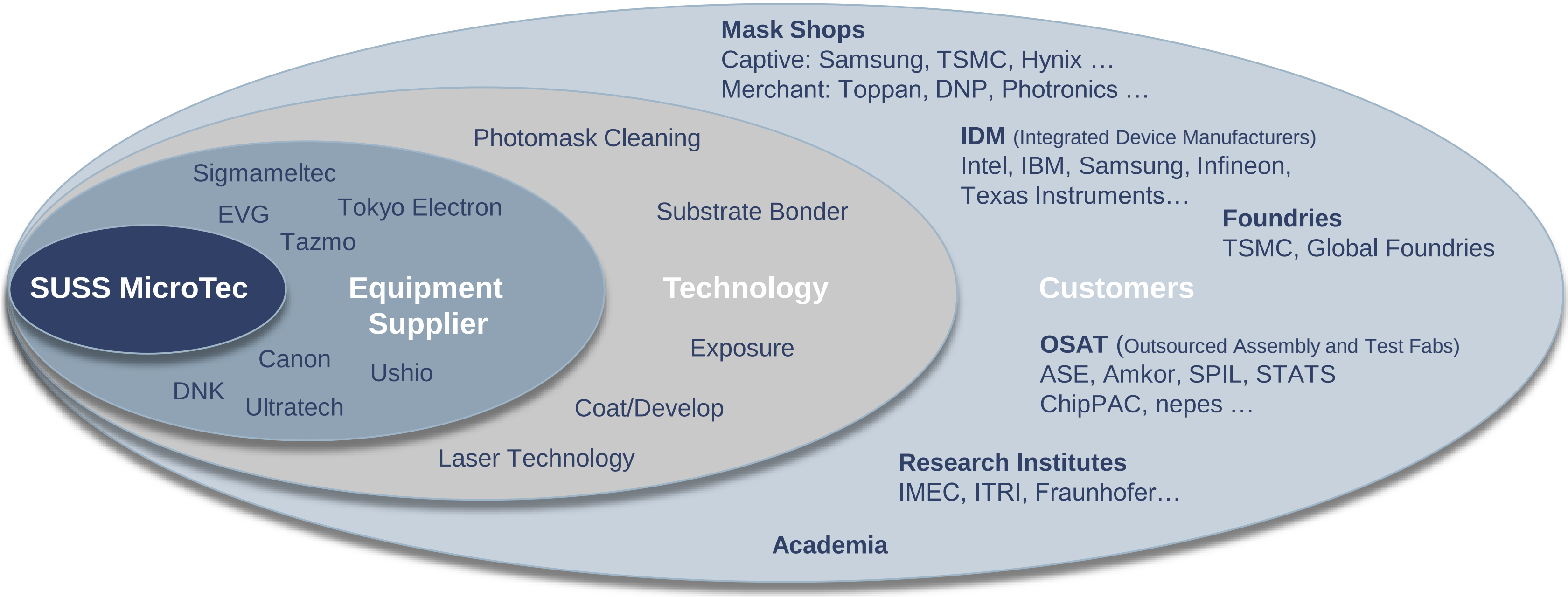


EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

MAIN COMPETITORS AND PEER GROUP



Peer Group	
BE Semiconductor:	equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy
Ultratech:	steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)
Kulicke & Soffa:	design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)
Rudolph Tech:	equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)
EV Group:	equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- + Production facility ~15,000 m²

Garching*

- + SUSS MicroTec HQ
- + Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- + Production facility ~9,000 m²

USA

Corona (California)

- + Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- + Production facility ~7,000 m²

*Production site is owned by SUSS MicroTec